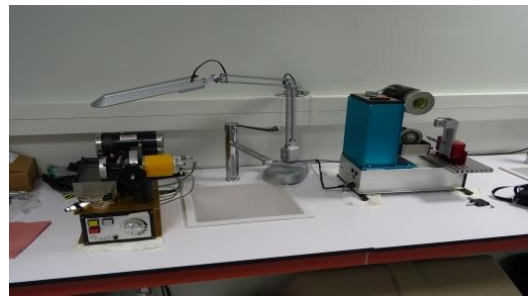


## Our services

Cut all substrates with an accuracy of 10  $\mu\text{m}$



### YOUR NEEDS

- Precision cutting of bare planar crystals or already structured crystals (deposits or microcomponents)

### RELATED SKILLS

- After cutting, the components can be fixed and electrically connected onto PCB cards
- For silicon, it is only possible to engrave with a diamond tip on "blue tape" at the surface, for subsequent cleavage
- Micro and nanofabrication processes

### OUR SOLUTIONS

- Disc saw for all materials up to 4 inches
- Resin-bonded horizontal wire saw for maximum positioning accuracy up to 3 inches
- Resin-bonded vertical wire saw for minimum mechanical stress suitable for thin and fragile substrates up to 3 inches
- "Wafer scriber" for silicon substrates up to 6 inches

### OUR REFERENCES


### KEYWORDS

Cutting, Scribbling, Microcomponents


### CONTACT


- Contact the research group:

 [juan-carlos.rojas-sanchez@univ-lorraine.fr](mailto:juan-carlos.rojas-sanchez@univ-lorraine.fr)

 +33 3 72 74 25 78

- Contact the technology transfer office (TTO):

 [ijl-tto@univ-lorraine.fr](mailto:ijl-tto@univ-lorraine.fr)

 +33 3 72 74 26 04